



SOT1325-1

plastic thermal enhanced very thin small outline package; no leads; 10 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON10
Package type industry code	HVSON10
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	17-4-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	1.7	-	mm
n ₂	actual quantity of termination	-	-	10	-	



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2. Package outline

HVSON10: plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 10 x 10 x 0.85 mm

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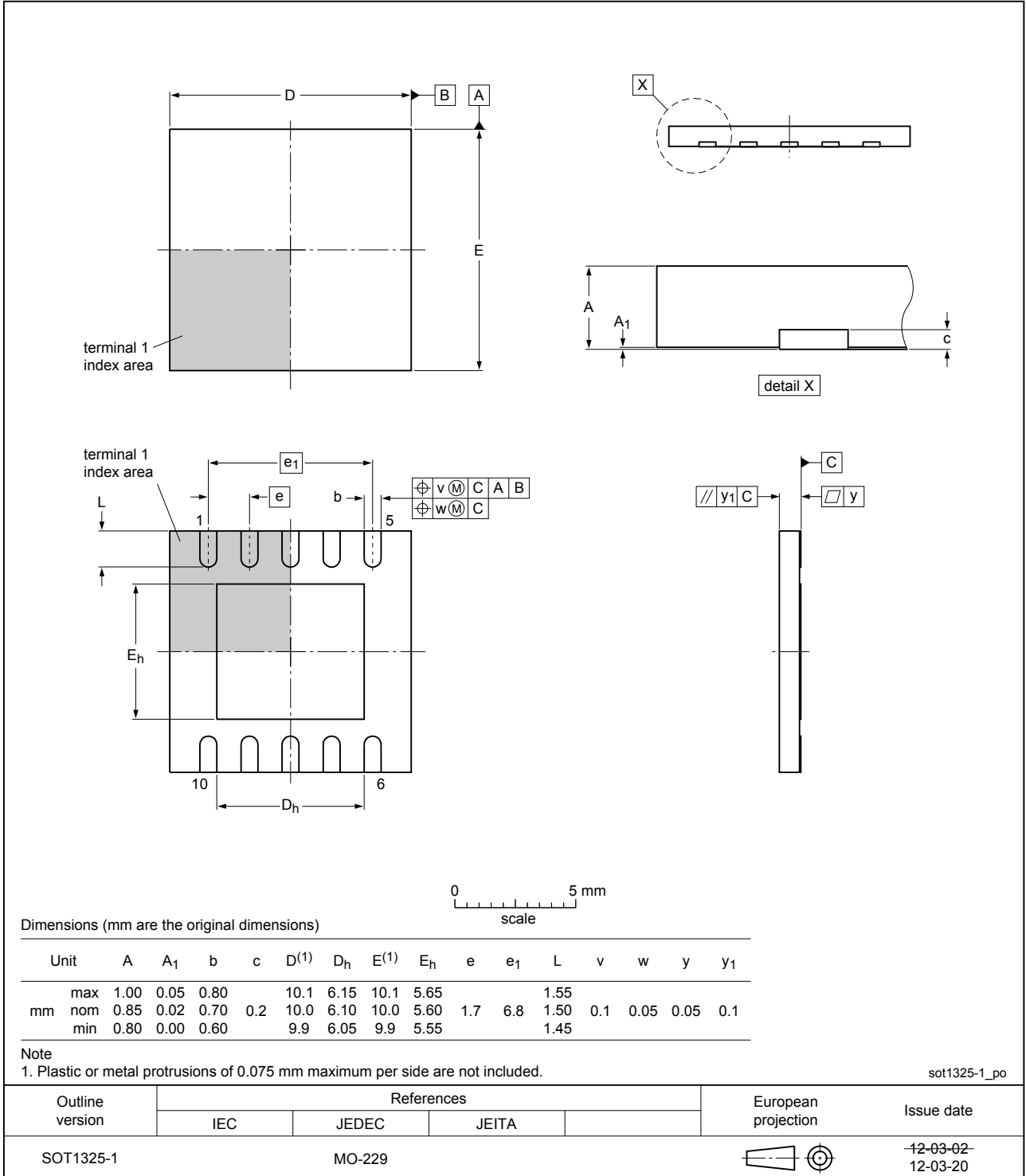


Fig. 1. Package outline HVSON10 (SOT1325-1)

3. Legal information

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